

## 50N03-VB Datasheet N-Channel 30-V (D-S) MOSFET

PRODUCT SUMMARY							
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A) <sup>a, e</sup>	Q <sub>g</sub> (Typ)				
30	0.007 at V <sub>GS</sub> = 10 V	80	31 nC				
	0.009 at V <sub>GS</sub> = 4.5 V	60	31110				

# **DFN5X6 Single** Top View Bottom View

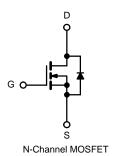
#### **FEATURES**

- Trench Power MOSFET
- 100 % R<sub>g</sub> and UIS Tested
   Compliant to RoHS Directive 2011/65/EU



#### **APPLICATIONS**

- OR-ing
- Server
- DC/DC



ABSOLUTE MAXIMUM RATINGS (TA	$_{\lambda}$ = 25 °C, unle	ess otherwise	noted)			
Parameter	Symbol	Limit		Unit		
Drain-Source Voltage		$V_{DS}$	30 ± 20		- V	
Gate-Source Voltage		V <sub>GS</sub>				
	$T_C = 25  ^{\circ}C$		80		A	
Continuous Drain Current (T <sub>.I</sub> = 175 °C)	T <sub>C</sub> = 70 °C	- I <sub>D</sub>	60			
Continuous Diam Current (1) = 173 C)	T <sub>A</sub> = 25 °C		<b>50</b> b, c			
	T <sub>A</sub> = 70 °C		45 <sup>b, c</sup>			
Pulsed Drain Current		I <sub>DM</sub>	210			
Avalanche Current Pulse	L = 0.1 mH	I <sub>AS</sub>	60			
Single Pulse Avalanche Energy		E <sub>AS</sub>	95		mJ	
Continuous Source-Drain Diode Current	T <sub>C</sub> = 25 °C	l <sub>a</sub>	80		А	
Continuous Source-Diam Diode Current	T <sub>A</sub> = 25 °C	- I <sub>S</sub>	60			
Maximum Power Dissipation	T <sub>C</sub> = 25 °C	D	155		14/	
Maximum i ower Dissipation	T <sub>C</sub> = 70 °C	P <sub>D</sub>	105		W	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 175		°C	
THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Тур.	Max.	Unit	
Maximum Junction-to-Ambient <sup>b, d</sup>	t ≤ 10 sec	R <sub>thJA</sub>	32	40	°C/W	
Maximum Junction-to-Case	Steady State	R <sub>thJC</sub>	0.5 0.6		· C/vv	

- a. Based on T<sub>C</sub> = 25 °C.
  b. Surface mounted on 1" x 1" FR4 board.

- d. Maximum under steady state conditions is 90 °C/W.
   e. Calculated based on maximum junction temperature. Package limitation current is 90 A.

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static					l		
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	30			V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	ΔVne/Tu		35		1406	
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	$I_D = 250  \mu A$		- 7.5		mV/°C	
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_D = 250 \mu A$	0.5		2.0	V	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zero Osto Vellana D. i. O i		$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}$			1	μА	
Zero Gate Voltage Drain Current	IDSS	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$			10		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	90			Α	
		$V_{GS} = 10 \text{ V}, I_D = 30.8 \text{ A}$		0.007			
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS} = 4.5 \text{ V}, I_D = 27 \text{ A}$		0.009		Ω	
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	$V_{DS} = 15 \text{ V}, I_{D} = 30.8 \text{ A}$		160		S	
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>				1180	pF	
Output Capacitance	C <sub>oss</sub>	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$			425		
Reverse Transfer Capacitance	C <sub>rss</sub>				170		
Total Cata Channa	Qg	$V_{DS} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 30.8 \text{ A}$			61	nC	
Total Gate Charge					31.5		
Gate-Source Charge	Q <sub>gs</sub>	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 27.8 \text{ A}$			10		
Gate-Drain Charge	$Q_{gd}$				6		
Gate Resistance	R <sub>g</sub>	f = 1 MHz		1.4	2.1	Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			18	27	ns	
Rise Time	t <sub>r</sub>	$V_{DD} = 15 \text{ V}, R_L = 0.625 \Omega$ $I_D \cong 24 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		11	17		
Turn-Off Delay Time	t <sub>d(off)</sub>			70	105		
Fall Time	t <sub>f</sub>			10	15		
Turn-On Delay Time	t <sub>d(on)</sub>			55	83		
Rise Time	t <sub>r</sub>	$V_{DD}$ = 15 V, $R_L$ = 0.67 $\Omega$		180	270		
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 22.5 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		55	83		
Fall Time	t <sub>f</sub>			12	18		
<b>Drain-Source Body Diode Characteristic</b>	cs						
Continuous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C		60		A	
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>			210		_ ^	
Body Diode Voltage	V <sub>SD</sub>	I <sub>S</sub> = 22 A		0.8	1.2	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>			52	78	ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	I <sub>F</sub> = 20 A, di/dt = 100 A/μs, T <sub>J</sub> = 25 °C		70.2	105	nC	
Reverse Recovery Fall Time	t <sub>a</sub>			27		ns	
Reverse Recovery Rise Time	t <sub>b</sub>			25			

#### Notes:

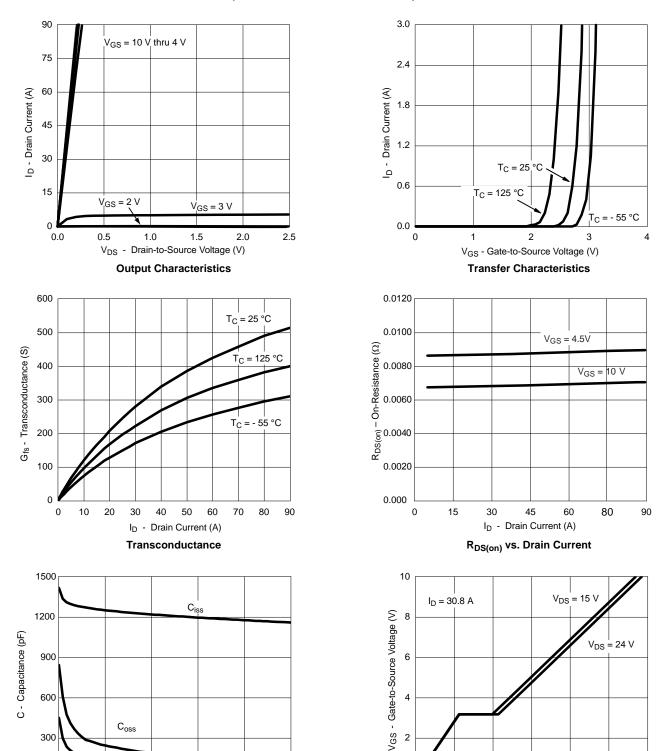
- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

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#### TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



2

30

60

90

Q<sub>g</sub> - Total Gate Charge (nC)

**Gate Charge** 

120

150

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 $C_{rss}$ 

18

V<sub>DS</sub> - Drain-to-Source Voltage (V) Capacitance

30

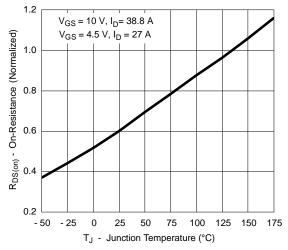
300

0

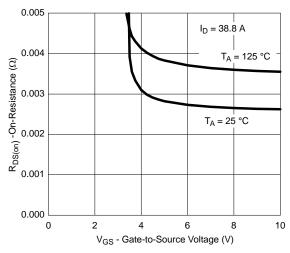
180



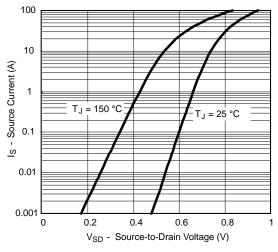
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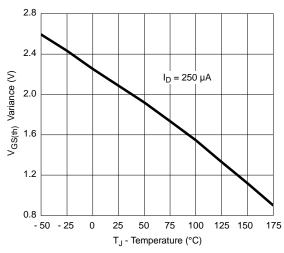
On-Resistance vs. Junction Temperature



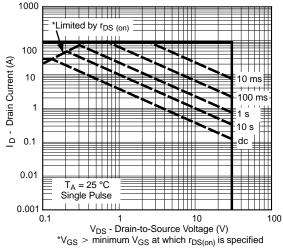
 $R_{DS(on)}\, vs.\, V_{GS}\, vs.\, Temperature$ 



Forward Diode Voltage vs. Temperature

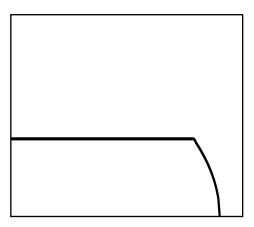


Threshold Voltage



Safe Operating Area, Junction-to-Ambient

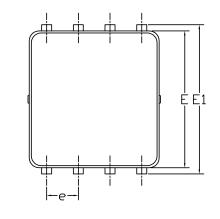
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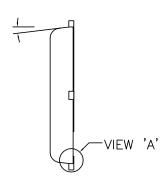


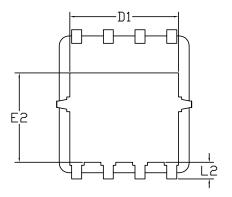
**Current Derating\*** 

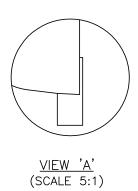
\*The power dissipation  $P_D$  is based on  $T_{J(max)}$  = 175 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

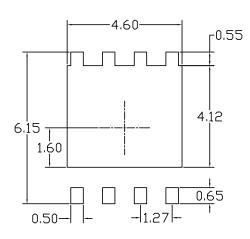




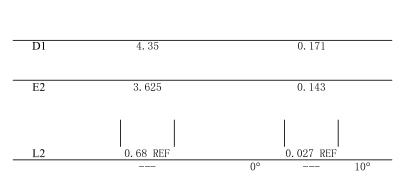








NOTE



UNIT: mm



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